

## RECEIVED AUG 14 2003 TC ADECORK

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IN THE UNITED STATES PATENT AND

In re application of WANG et al.

S/N: 09/583,599

Filed: May 31, 2000

For: "Improved Acid Copper Electroplating Solutions"

Atty. Dkt.: 99A209

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Art Unit: 1711

Examiner: Thao T. Tran

## **CERTIFICATE OF MAILING**

I hereby certify that this correspondence and every writing referred to herein as being enclosed is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on august 7,2003 (Date)

Betty Lee

Signature of person mailing

Printed name of person signing this certificate

Dear Sir:

## AMENDMENT AND RESPONSE TO OFFICE ACTION

In response to the Office Action mailed May 21, 2003, please enter the following amendments.